

# 2.0A LOW VF SCHOTTKY BARRIER RECTIFIER

### PowerDI<sup>®</sup>123

### **Features**

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- High Surge Capability
- High Current Capability and Low Forward Voltage Drop
- Lead Free Finish, RoHS Compliant (Note 4)
- "Green" Molding Compound (No Br, Sb)
- Qualified to AEC-Q101 Standards for High Reliability

## **Mechanical Data**

- Case: PowerDI<sup>®</sup>123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish Matte Tin Annealed Over Copper leadframe. Solderable per MIL-STD-202, Method 208 63
- Marking Information: See Page 2
- Ordering Information: See Page 2
- Weight: 0.01 grams (approximate)



Top View

### **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>R</sub> WM	40	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Average Forward Current	I <sub>F(AV)</sub>	2.0	А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	50	А

### Thermal Characteristics

Characteristic	Symbol	Тур	Max	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	_	1.67	W
Power Dissipation (Note 2)	P <sub>D</sub>	_	556	mW
Thermal Resistance Junction to Ambient (Note 1)	$R_{ heta JA}$	60	_	°C/W
Thermal Resistance Junction to Ambient (Note 2)	$R_{ heta JA}$	180	_	°C/W
Thermal Resistance Junction to Soldering (Note 3)	$R_{ heta JS}$	_	5	°C/W
Operating Temperature Range (See figure 4)	TJ	-55 to +125		°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150		°C

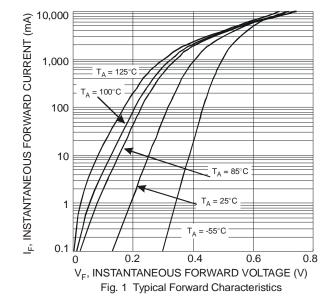
### **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

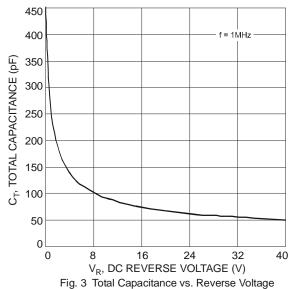
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	40		_	V	$I_R = 500 \mu A$
		_	0.4	0.45	V	I <sub>F</sub> = 1.0A
Forward Voltage	VF	_	0.45	0.50		I <sub>F</sub> = 2.0A
		_	0.50	0.65		$I_F = 3.0A$
		_	_	0.1		V <sub>R</sub> = 40V
Leakage Current (Note 5)	1_	_	_	10		$V_R = 40V, T_J = 85^{\circ}C$ $V_R = 20V$
Leakage Current (Note 5)	I <sub>R</sub>	_	_	0.05	IIIA	$V_R = 20V$
		_	_	5		$V_R = 20V, T_J = 85^{\circ}C$
Total Capacitance	C <sub>T</sub>	_	90	_	pF	$V_R = 10V, f = 1.0MHz$

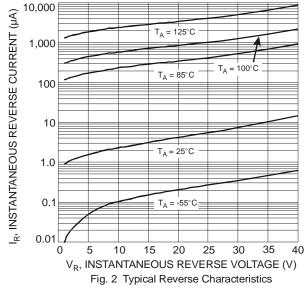
Notes:

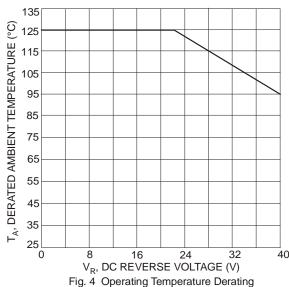
- 1. Part mounted on 50.8mm X 50.8mm GETEK board with 25.4mm X 25.4mm copper pad, 25% anode, 75% cathode.
- 2. Part mounted on FR-4 board with 1.8mm X 2.5mm cathode and 1.8mm X 1.2mm anode, 1 oz. copper pads.
- 3. Theoretical  $R_{\text{NJS}}$  calculated from the top center of the die straight down to the PCB cathode tab solder junction.
- 4. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/products/lead\_free.html.
- 5. Short duration pulse test used to minimize self-heating effect.











## Ordering Information (Note 6)

Part Number	Case	Packaging
DFLS240L-7	PowerDI <sup>®</sup> 123	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

## Marking Information



F06A = Product Type Marking Code YM = Date Code Marking Y = Year (ex: T = 2006)

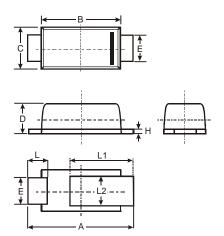
M = Month (ex: 9 = September)

Date Code Key

Year	2004	20	005	2006	2007	20	800	2009	2010	20	11	2012
Code	R	;	S	T	U		V	W	Х	,	Y	Z
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

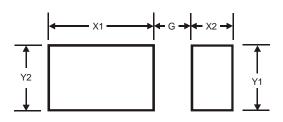


# **Package Outline Dimensions**



PowerDI <sup>®</sup> 123					
Dim	Min	Max	Тур		
Α	3.50	3.90	3.70		
В	2.60	3.00	2.80		
С	1.63	1.93	1.78		
D	0.93	1.00	0.98		
Е	0.85	1.25	1.00		
Н	0.15	0.25	0.20		
L	0.55	0.75	0.65		
L1	1.80	2.20	2.00		
L2	0.95	1.25	1.10		
All Dimensions in mm					

# **Suggested Pad Layout**



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4



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